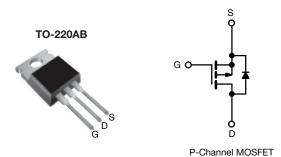


Power MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	-60	-60			
$R_{DS(on)}(\Omega)$	V _{GS} = -10 V	0.50			
Q _g max. (nC)	12	12			
Q _{gs} (nC)	3.8	3.8			
Q _{gd} (nC)	5.1	5.1			
Configuration	Sing	Single			

FEATURES

- Dynamic dV/dt rating
- Repetitive avalanche rated
- P-channel
- 175 °C operating temperature
- · Fast switching
- · Ease of paralleling
- Simple drive requirements
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

Note

This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

DESCRIPTION

Third generation power MOSFETs from Vishay provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-220AB package is universally preferred for all commercial-industrial applications at power dissipation levels to approximately 50 W. The low thermal resistance and low package cost of the TO-220AB contribute to its wide acceptance throughout the industry.

ORDERING INFORMATION				
Package	TO-220AB			
Lead (Pb)-free	IRF9Z14PbF			
Lead (Pb)-free and halogen-free	IRF9Z14PbF-BE3			

ABSOLUTE MAXIMUM RATINGS (T _C	= 25 °C, unl	ess otherwis	se noted)			
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V_{DS}	-60	.,,	
Gate-source voltage			V_{GS}	± 20	_ V	
Continuous dusin surrent	1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1, 1	T _C = 25 °C	I _D	-6.7		
Continuous drain current	V _{GS} at 10 V	$T_C = 25 ^{\circ}C$ $T_C = 100 ^{\circ}C$		-4.7	А	
Pulsed drain current a			I _{DM}	-27		
Linear derating factor				0.29	W/°C	
Single pulse avalanche energy b			E _{AS}	140	mJ	
Repetitive avalanche current a			I _{AR}	-6.7	А	
Repetitive avalanche energy ^a			E _{AR}	4.3	mJ	
Maximum power dissipation $T_C = 25$ °C			P_{D}	43	W	
Peak diode recovery dV/dt ^c			dV/dt	-4.5	V/ns	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +175	00	
Soldering recommendations (peak temperature) d For 10 s			-	300	°C	
Mounting torque	6-32 or M3 screw			10	lbf ⋅ in	
				1.1	N⋅m	

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. V_{DD} = -25 V, starting T_J = 25 °C, L = 3.6 mH, R_g = 25 Ω , I_{AS} = -6.7 A (see fig. 12)
- c. $I_{SD} \le -6.7$ A, $dI/dt \le 90$ A/ μ s, $V_{DD} \le V_{DS}$, $T_J \le 175$ °C
- d. 1.6 mm from case



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THERMAL RESISTANCE RATINGS						
PARAMETER	SYMBOL	TYP.	MAX.	UNIT		
Maximum junction-to-ambient	R _{thJA}	-	62			
Case-to-sink, flat, greased surface	R _{thCS}	0.50	-	°C/W		
Maximum junction-to-case (drain)	R _{thJC}	-	3.5			

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$		-60	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference	to 25 °C, I _D = -1 mA	-	-0.060	-	V/°C
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = \	/ _{GS} , I _D = -250 μA	-2.0	-	-4.0	V
Gate-source leakage	I _{GSS}	V	V _{GS} = ± 20 V		-	± 100	nA
Zero gate voltage drain current	I _{DSS}		-60 V, V _{GS} = 0 V V _{GS} = 0 V, T _J = 150 °C	-	-	-100 -500	μΑ
Drain-source on-state resistance	R _{DS(on)}		I _D = -4.0 A ^b		_	0.50	Ω
Forward transconductance			25 V, I _D = -4.0 A ^b	1.4	_	-	S
Dynamic	9 _{fs}	VDS - Z	-5 V, ID - 4.0 A	1.7			
Input capacitance	C _{iss}			_	270	_	pF
Output capacitance	C _{oss}		$V_{GS} = 0 \text{ V},$ $DS = -25 \text{ V},$	_	170	_	
Reverse transfer capacitance	C _{rss}		MHz, see fig. 5	_	31	_	
Total gate charge	Q _g	1			-	12	
Gate-source charge	Q _{gs}	Voc = -10 V	$V_{GS} = -10 \text{ V}$ $I_D = -6.7 \text{ A}, V_{DS} = -48 \text{ V},$ see fig. 6 and 13 b		_	3.8	nC
Gate-drain charge	Q _{gd}	- VGS - 10 V			_	5.1	
Turn-on delay time	t _{d(on)}			-	11	-	
Rise time	t _r	Vpp = -	30 V, I _D = -6.7 A,	-	63	-	1
Turn-off delay time	t _{d(off)}	$V_{DD} = -30 \text{ V}, I_D = -6.7 \text{ A},$ $R_g = 24 \Omega, R_D = 4.0 \Omega, \text{ see fig. } 10^{\text{ b}}$		-	10	-	ns
Fall time	t _f			-	31	-	
Gate input resistance	R _q	f = 1 MHz, open drain		1.4	-	8.7	Ω
Internal drain inductance	L _D	Between lead, 6 mm (0.25") from		-	4.5	-	.11
Internal source inductance	L _S		package and center of die contact		7.5	-	- nH
Drain-Source Body Diode Characteristic	cs						
Continuous source-drain diode current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		ı	-	-6.7	
Pulsed diode forward current ^a	I _{SM}			-	-	-27	- A
Body diode voltage	V _{SD}	T _J = 25 °C, I _S = -6.7 A, V _{GS} = 0 V ^b		-	-	-5.5	V
Body diode reverse recovery time	t _{rr}	$T_J = 25 ^{\circ}\text{C}, I_F = -6.7 \text{A}, \text{dI/dt} = 100 \text{A/}\mu\text{s}^{\text{b}}$		-	80	160	ns
Body diode reverse recovery charge	Q _{rr}			-	0.096	0.19	μC
Forward turn-on time	t _{on}	Intrinsic turr	n-on time is negligible (turn	on is do	minated b	v Ls and	Ln)

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11)
- b. Pulse width \leq 300 µs; duty cycle \leq 2 %



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

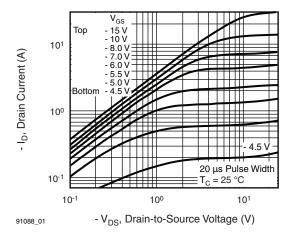


Fig. 1 - Typical Output Characteristics, T_C = 25 °C

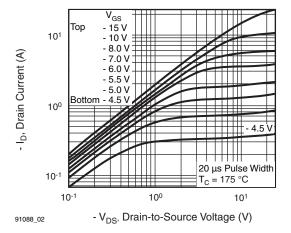


Fig. 2 - Typical Output Characteristics, T_C = 175 $^{\circ}$ C

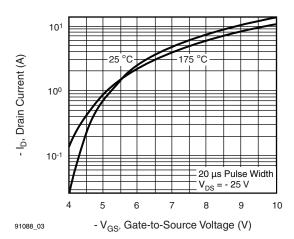


Fig. 3 - Typical Transfer Characteristics

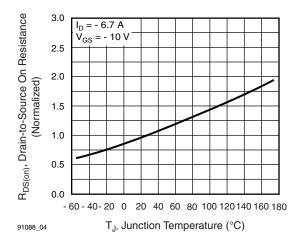


Fig. 4 - Normalized On-Resistance vs. Temperature

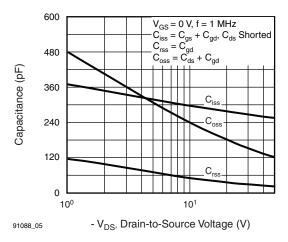


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

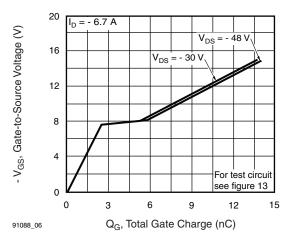


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage



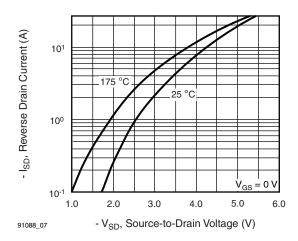


Fig. 7 - Typical Source-Drain Diode Forward Voltage

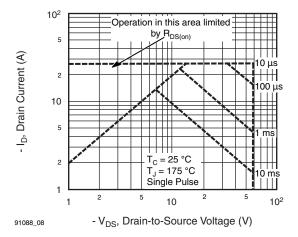


Fig. 8 - Maximum Safe Operating Area

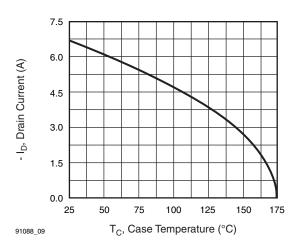


Fig. 9 - Maximum Drain Current vs. Case Temperature

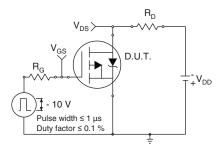


Fig. 10a - Switching Time Test Circuit

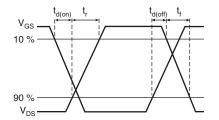


Fig. 10b - Switching Time Waveforms

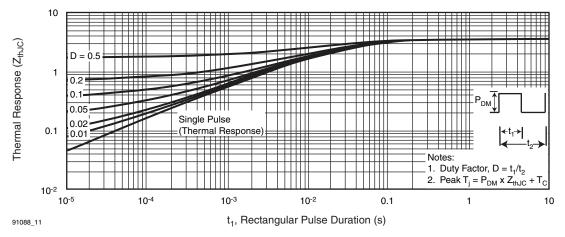


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case



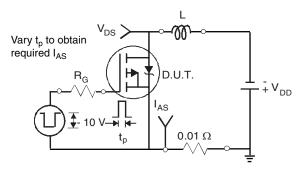


Fig. 12a - Unclamped Inductive Test Circuit

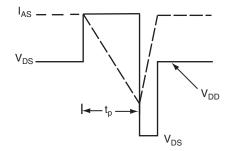


Fig. 12b - Unclamped Inductive Waveforms

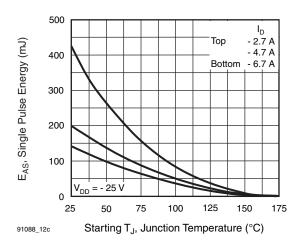


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

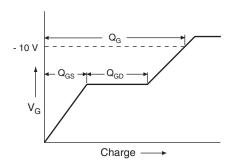


Fig. 13a - Basic Gate Charge Waveform

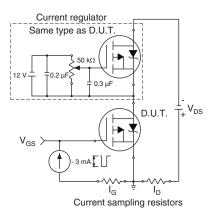
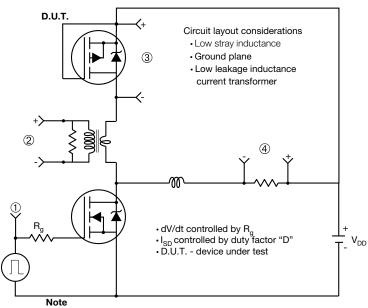


Fig. 13b - Gate Charge Test Circuit



Peak Diode Recovery dV/dt Test Circuit



· Compliment N-Channel of D.U.T. for driver

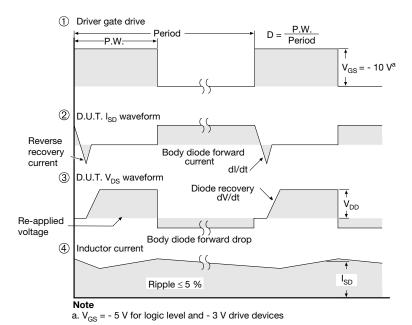
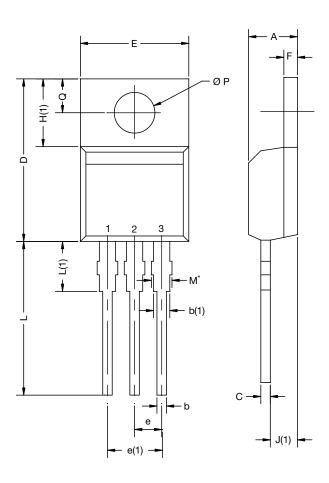


Fig. 14 - For P-Channel

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TO-220-1



DIM.	MILLIN	METERS	INC	HES		
	MIN.	MAX.	MIN.	MAX.		
A	4.24	4.65	0.167	0.183		
b	0.69	1.02	0.027	0.040		
b(1)	1.14	1.78	0.045	0.070		
С	0.36	0.61	0.014	0.024		
D	14.33	15.85	0.564	0.624		
Е	9.96	10.52	0.392	0.414		
е	2.41	2.67	0.095	0.105		
e(1)	4.88	5.28	0.192	0.208		
F	1.14	1.40	0.045	0.055		
H(1)	6.10	6.71	0.240	0.264		
J(1)	2.41	2.92	0.095	0.115		
L	13.36	14.40	0.526	0.567		
L(1)	3.33	4.04	0.131	0.159		
ØР	3.53	3.94	0.139	0.155		
Q	2.54	3.00	0.100	0.118		
ECN: E21-0621-Rev. D, 04-Nov-2021 DWG: 6031						

Note

• $M^* = 0.052$ inches to 0.064 inches (dimension including protrusion), heatsink hole for HVM



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